

| no-clean products | solids (%) | activity alloys | main process use | application | |
|---------------------|--------------|-------------------------|--------------------|--|-----------------------------|
| Flux | | | | | |
| IF 2005M | 1,8 | OR L0 SnPb and Pb-free | alcohol based | no-residue™ - SnPb wave soldering | foam, spray, jet, dip, pen |
| IF 2005K | 2,5 | OR L0 Pb-free and SnPb | alcohol based | Pb-free wave soldering | foam, spray, jet, dip, pen |
| IF 2005C | 3,4 | OR L0 SnPb and Pb-free | alcohol based | selective soldering | foam, spray, jet, dip, pen |
| PacIFic 2009M | 3,7 | OR L0 SnPb and Pb-free | water based | wave soldering | spray, jet |
| PacIFic 2009MLF-E | 3,7 | OR L0 SnPb and Pb-free | water based | selective and wave soldering, lowers solder balls | spray, jet |
| PacIFic 2009MLF | 3,7 | OR L0 SnPb and Pb-free | water based | selective and wave soldering, anti solder ball | spray, jet |
| PacIFic 2010F | 2,5 | OR L0 SnPb and Pb-free | water based | wave soldering, foam fluxing | foam, spray, jet |
| PacIFic 2011F | 3,7 | OR L0 Sn Pb and Pb-free | water based | wave soldering, foam fluxing, increased activity | foam, spray, jet |
| IF 3006 | 3,2 | OR L0 SnPb and Pb-free | low VOC | wave and selective soldering | foam, spray, jet |
| Repair flux | | | | | |
| IF 8001 | 8,55 | RE L0 SnPb and Pb-free | alcohol based | low residue manual soldering | pen, brush |
| IF 6000 | 7,55 | RO L0 SnPb and Pb-free | alcohol based | BGA repair, manual soldering | pen, brush |
| Gel flux | | | | | |
| | viscosity | | | | |
| IF 8300 | 210 kcps | RE L0 SnPb and Pb-free | gel flux | repair, BGA soldering | syringe, brush |
| IF 8300-4 | 70 kcps | RE L0 SnPb and Pb-free | gel flux | repair, BGA soldering | brush |
| IF 8300-6 | 25 kcps | RE L0 SnPb and Pb-free | gel flux | repair, BGA soldering | brush |
| WSGF 2006 | | OR M0 SnPb and Pb-free | gel flux | water soluble* repair, BGA soldering | brush |
| | flux content | | | | |
| Solder wire | | | | | |
| IF 14-06 | 0,6 | RE L0 SnPb | no-residue™ | SMD soldering, repair | manual soldering |
| IF 14-09 | 0,9 | RE L0 SnPb | very low residue | manual soldering, repair | manual soldering |
| IF 14-10 | 1,0 | RE L0 SnPb | very low residue | manual soldering, repair | manual soldering |
| IF 14-14 | 1,4 | RE L0 SnPb | low residue | easy brushable, manual soldering, repair | manual soldering |
| IF 14-16 | 1,6 | RE L0 Pb-free | low residue | easy brushable, manual soldering, repair | manual soldering |
| IF 14-22 | 2,2 | RE L0 Pb-free | fast wetting | high thermal mass, through hole soldering, repair | manual, automated soldering |
| Flexsol 903 | 2,2 - 3,5 | RO L0 Pb-free | fast wetting | low spatting, manual, automated soldering, repair | manual, automated soldering |
| IF R88 | 0,9-2,2-3,5 | RO L1 SnPb, Pb-free | extra activity | manual, automated soldering, repair | manual, automated soldering |
| Solder paste | | | | | |
| DP 5505 | | RO L0 SnPb and Pb-free | anti hidden pillow | general first choice paste, air or N ₂ | printing, dispensing |
| IF 9009Lt | | RE L1 SnPb and Pb-free | extra activity | difficult to solder surfaces | printing, dispensing |
| Delphine 5504 | | RE L0 Pb-free, high Pb | high melt alloys | Pb-free, component manuf., high melting point alloys | printing, dispensing |
| WSP 2006 | | OR M0 SnPb and Pb-free | water washable | water soluble*, easy post reflow cleaning | printing, dispensing |

* water soluble means post reflow residue always has to be cleaned. This is not a no-clean process